

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A material comprising:
a conductive paste containing including a conductive material, an acrylic system resin as a binder and at least one solvent selected from a group consisting of limonene, α -terpinyl acetate, I-dihydrocarvyl acetate, I-menthone, I-perillyl acetate, I-carvyl acetate, and d-dihydrocarvyl acetate as a solvent.
2. (Currently Amended) ~~A conductive paste~~ The material in accordance with Claim 1, wherein the weight-average molecular weight of the acrylic system resin is equal to or larger than 450,000 and equal to or smaller than 900,000.
3. (Currently Amended) ~~A conductive paste~~ The material in accordance with Claim 1, wherein the acid value of the acrylic system resin is equal to or larger than 5 mgKOH/g and equal to or smaller than 25 mgKOH/g.
4. (Currently Amended) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component comprising a step of printing a conductive paste containing including a conductive material, an acrylic system resin as a binder and at least one solvent selected from a group consisting of limonene, α -terpinyl acetate, I-dihydrocarvyl acetate, I-menthone, I-perillyl acetate, I-carvyl acetate, and d- dihydrocarvyl acetate as a solvent on a ceramic green sheet containing a butyral system resin as a binder in a pattern to form an electrode layer.

5. (Currently Amended) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 4, which further comprises a step of printing a dielectric paste ~~containing including a dielectric material, an~~ acrylic system resin as a binder and at least one solvent selected from a group consisting of limonene, α -terpinyl acetate, I-dihydrocarvyl acetate, I-menthone, I-perillyl acetate, I-carvyl acetate, and d-dihydrocarvyl acetate as a solvent on the ceramic green sheet in a pattern complimentary to the pattern of the electrode layer after drying the electrode layer, thereby forming a spacer layer.

6. (Currently Amended) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 4, which further comprises a step of printing a dielectric paste ~~containing including a dielectric material, an~~ acrylic system resin as a binder and at least one solvent selected from a group consisting of limonene, α -terpinyl acetate, I-dihydrocarvyl acetate, I-menthone, I-perillyl acetate, I-carvyl acetate, and d-dihydrocarvyl acetate as a solvent on the ceramic green sheet in a pattern complimentary to the pattern of the electrode layer prior to forming the electrode layer, thereby forming a spacer layer.

7. (Previously Presented) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 4, wherein the weight-average molecular weight of the acrylic system resin is equal to or larger than 450,000 and equal to or smaller than 900,000.

8. (Previously Presented) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 4, wherein the acid value of the acrylic system resin is equal to or larger than 5 mgKOH/g and equal to or smaller than 25 mgKOH/g.

9. (Previously Presented) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 4, wherein the degree of polymerization of the butyral system resin is equal to or larger than 1,000.

10. (Previously Presented) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 4, wherein the butyral degree of the butyral system resin is equal to or larger than 64 mol % and equal to or smaller than 78 mol %.

11. (New) A material in accordance with Claim 1, wherein the conductive material is selected from a group consisting of Ni, Ni alloy and a mixture thereof.

12. (New) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 4, wherein the conductive material is selected from a group consisting of Ni, Ni alloy and a mixture thereof.